



VIA Labs, Inc.

Data Sheet

VL152 (B1)

E-Marker for USB Type-C Cable

Nov. 9th, 2017

Revision 1.00



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Revision History

Rev	Date	Note	Initial
0.90	06/12/2017	Preliminary Release	TH
0.91	07/26/2017	Update Operation Power Consumption	TH
1.00	11/09/2017	Official Release and Add Note in Ordering Information	TH

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Product Feature

VL152

Electronic Marker for USB Type-C Passive Cable

■ PD 3.0 Compliant

- Compliant to USB Power Delivery 3.0 Specification
- SOP' Endpoint
- Supports Programming over CC Line using Unstructured Vendor Defined Messages

■ Sideband Signal Support

- Supports SMBus for Programming and Debugging

■ Easy Manufacturability

- DFN-8 2x3mm features 0.5mm pin pitch for easy manufacturing
- WLCSP-6 1.2x1.25mm with 0.4mm pin pitch to minimize paddle card size.
- Compatible with standard PCB Process
- TMTP Programming Support over CC or SMBus
- Extremely Low BOM Cost: Diodes, Ra are all integrated On-Die
- Compatible with Third-Party Programming Tools

■ TMTP Memory Onboard

- Supports Triple-Time Writable memory to store Cable VDO, Certification Status VDO, Product VDO, etc.
- Features write-protection support so finished cables cannot be modified
- TMTP memory is the best choice for data-retention and longevity, can programing three times

■ Applications

- USB Type-C Cables such as Full-Featured C-to-C cables

■ Certification

- Earned USB-IF certification TID # 1030051 XID # 0000900

■ Misc.

- Optimized for Low Power consumption

Block Diagram

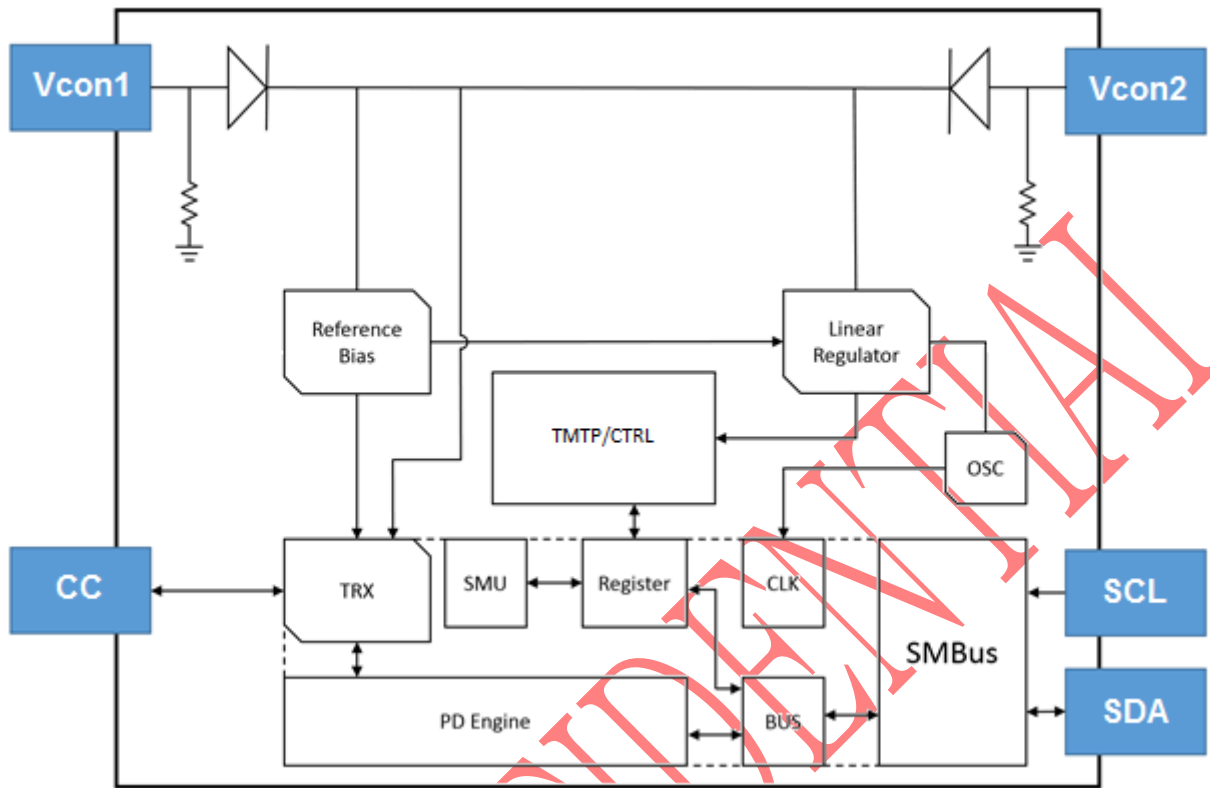


Figure 1 - Block Diagram

Pinout

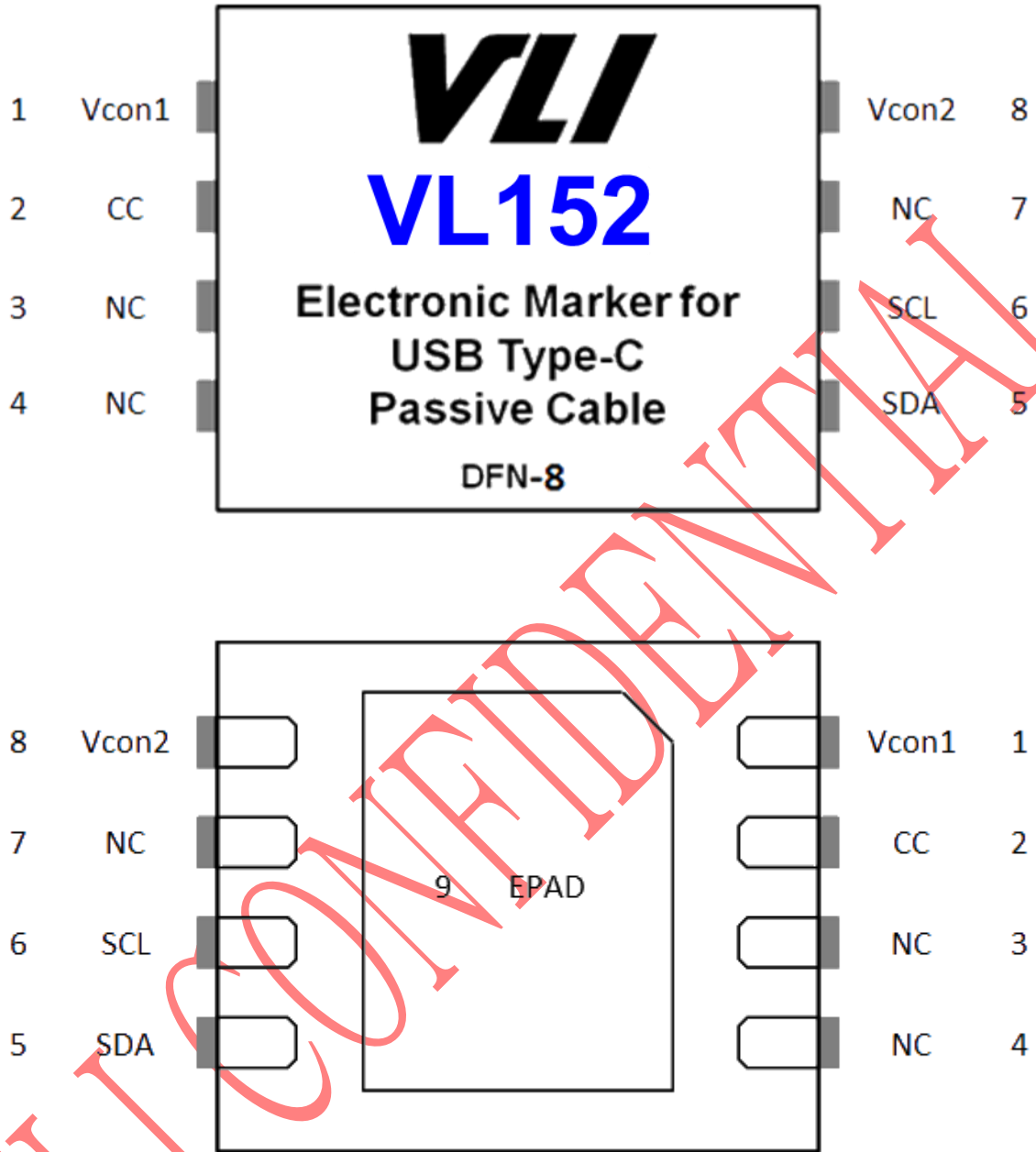
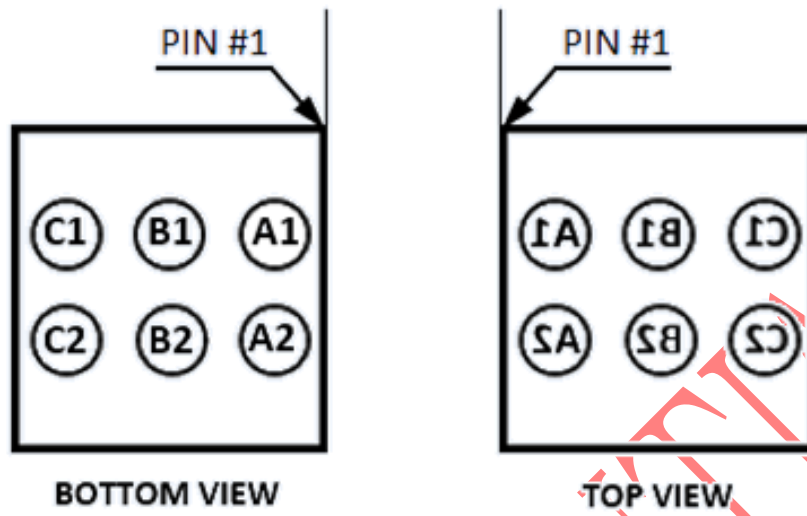


Figure 2 - Pin Diagram (DFN-8)



A1:	SDA	A2:	GND
B1:	SCL	B2:	CC
C1:	Vcon2	C2:	Vcon1

Figure 3 - Pin Diagram (WLCSP-6)

Pin List

DFN-8

Pin	Pin Name	Pin	Pin Name
1	Vcon1	5	SDA
2	CC	6	SCL
3	NC	7	NC
4	NC	8	Vcon2
		9	EPAD

WLCSP-6

Pin	Pin Name	Pin	Pin Name
A1	SDA	A2	GND
B1	SCL	B2	CC
C1	Vcon2	C2	Vcon1

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Pin Descriptions

Signal Type Definition

Name	Type	Signal Description
Input	I	A Logic Input Only Signal
Output	O	A Logic Output Only Signal
Input/ Output	I/O	A Logic Bi-Directional Signal
Power	PWR	A Power Pin
Ground	GND	A Ground Pin

Type-C Interface

Pin Name	Pin #DFN-8	Pin #WLCSP-6	I/O	Signal Description
Vcon1	1	C2	PWR	VCONN Power (Near Side)
CC	2	B2	I/O	CC communication line
Vcon2	8	C1	PWR	VCONN Power (Far Side)

Sideband & Miscellaneous

Pin Name	Pin#DFN-8	Pin #WLCSP-6	I/O	Signal Description
SCL	6	B1	I	SMBus Clock (Open Drain)
SDA	5	A1	I/O	SMBus Data (Open Drain)
NC	3,4,7	-	-	Not Connected (Float)

Ground

Pin Name	Pin #DFN-8	Pin #WLCSP-6	I/O	Signal Description
EPAD	9	A2	GND	Exposed Pad; System Ground

Electrical Specification

Absolute Maximum Rating

Symbol	Parameter	Min	Max	Unit	Note
T _{STG}	Storage Temperature	-55	125	°C	-
V _{CON1/2}	VCONN	-0.5	7	V	-
V _{ESD}	Electrostatic Discharge	-8000	8000	V	Human Body Model
θ _{jc}	Thermal resistance between junction and case	72.8	-	°C/W	4L PCB definitions follow JESD51-7 for WLCSP
P _D	Max Power Dissipation	-	1.24	W	

Note 1: Stress above conditions may cause permanent damage to the device.

Functional operation of this device should be restricted to the conditions described.

Note 2: About thermal factors, T_a is the concerned ambient temperature, and

$$\theta_{ca} = \theta_{ja} - \theta_{jc}$$

$$T_j = \theta_{ja} * P_D + T_a$$

$$T_c = \theta_{ca} * P_D + T_a$$

Operating Conditions

Symbol	Parameter	Min	Tpy	Max	Unit	Note
T _A	Ambient Temperature	-25		85	°C	-
T _j	Junction Temperature	-40		125	°C	-
V _{CON1/2}	VCONN	2.7		5.5	V	-
P _D	Power Consumption – operation	-	40		mW	-
P _D	Power Consumption - Suspend	-	0.8		mA	-

Electrical Characteristics

VDD=5V, TA=25°C (unless otherwise noted)

Common Normative Signaling Requirements						
Symbol	Parameter	Test Condition	Min	Typ	Max	Unit
fBitRate	Bit rate	-	270	300	330	kbps
pBitRate	Maximum difference between the bit-rate during the part of the packet following the Preamble and the reference bit-rate.	-			0.25	%
tInterFrameGap	Time from the end of last bit of a Frame until the start of the first bit of the next Preamble.	-	25			us
tStartDrive	Time before the start of the first bit of the Preamble when the transmitter shall start driving the line.	-	-1		1	us

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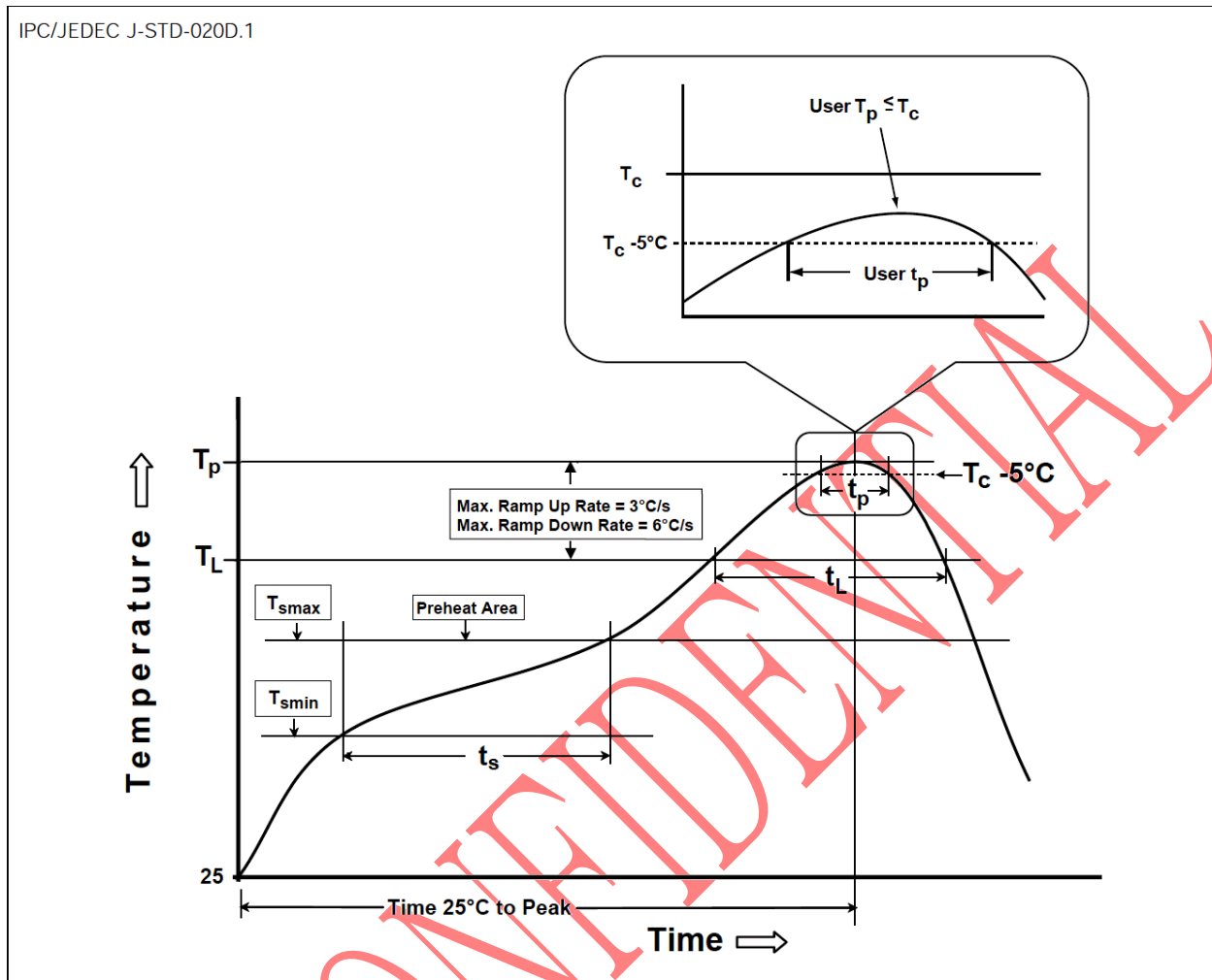
Default VDM Register Map

This table shows the default VDM TMTP section address mapping to Discover Identity Command ACK response message, which VL152 sends when receiving a Discover Identity command, if VL152 has not been programmed. Once VL152 TMTP is programmed, the default values will be discarded and VL152 will respond to Discover Identity command with the programmed values.

Address	bits	Description
Cable VDO		
0x8010	[7:4]	HW Version Number assigned by vendor, 0000b...1111b. 0000b [Default]
	[3:0]	Firmware Version Number, assigned by vendor, 0000b...1111b 0000b [Default]
0x8011	[7:5]	Version number of VDO, Version 1.0=000b, Values 001b...111b are Reserved Shall Not be used 000b [Default]
	[4]	Reserved 0 [Default]
	[3:2]	Type-C Plug to Type-C/Captive 00b = Reserved, Shall Not be used 01b = Reserved, Shall Not be used 10b = USB Type-C [Default] 11b = Captive
	[1]	Reserved 0 [Default]
	[0]	Cable Latency 0000b - Reserved, shall not be used 0001b - <10ns (~1m) [Default] 0010b - 10ns to 20ns (~2m) 0011b - 20ns to 30ns (~3m) 0100b - 30ns to 40ns (~4m) 0101b - 40ns to 50ns (~5m) 0110b - 50ns to 60ns (~6m) 0111b - 60ns to 70ns (~7m) 1000b - 1000ns (~100m) 1001b - 2000ns (~200m) 1010b - 3000ns (~300m) 1011b ...1111b Reserved, shall not be used Includes latency of electronics in Active Cable
0x8012	[4:3]	Cable Termination Type 00b = VCONN not required 01b = VCONN required [Default] 10b...11b Reserved, Shall Not be used
	[2:1]	Maximum cable VBus Voltage 00b = 20V [Default] 01b = 30V 10b = 40V 11b = 50V
	[0]	Reserved 0 [Default]

Address	bits	Description
0x8013	[7]	Reserved 0 [Default]
	[6:5]	VBUS Current Handling Capability 00b = Reserved, shall not be used 01b = 3A [Default] 10b = 5A 11b = Reserved, shall not be used.
	[4:3]	Reserved 00 [Default]
	[2:0]	USB SuperSpeed Signaling Support 000b = USB 2.0 only 001b = USB 3.1 Gen1 010b = USB 3.1 Gen1 and Gen2 [Default] 011b.. 111b = Reserved, shall not be used
Product VDO		
0x8014	[7:0]	USB Product ID, 16-bit unsigned integer, assigned by the cable vendor 00000000b, 00000000b [Default]
0x8015	[7:0]	
0x8016	[7:0]	Device version, bcdDevice , 16-bit unsigned integer, assigned by the cable vendor 00000000b, 00000000b [Default]
0x8017	[7:0]	
Cert Stat VDO		
0x8020	[7:0]	32-bit unsigned integer, USB-IF assigned XID for this cable 00000000b x4 [Default]
0x8021	[7:0]	
0x8022	[7:0]	
0x8023	[7:0]	
ID Header		
0x8024	[7]	Data Capable as USB Host <ul style="list-style-type: none"> ● Shall be set to one if the product is capable of enumerating USB Devices. ● Shall be set to zero otherwise. 0b [Default]
	[6]	Data Capable as a USB Device <ul style="list-style-type: none"> ● Shall be set to one if the product is capable of enumerating as a USB Device. ● Shall be set to zero otherwise 0b [Default]
	[5:3]	Product Type (cable plug) 000b – Undefined 001b...010b–Reserved, shall not be used. 011b–Passive Cable [Default] 100b–Active Cable 101b...111b–Reserved, shall not be used.
	[2]	Modal Operation Supported <ul style="list-style-type: none"> ● Shall be set to one if the product supports Modal Operation. ● Shall be set to zero otherwise 0b [Default]
	[1:0]	Reserved
0x8025	[7: 0]	00b, 0000000b [Default]
0x8026	[7:0]	USB Vendor ID, 16-bit unsigned integer 00100001b(21), 00001001b(09) [Default]
0x8027	[7:0]	

General Reflow Profile Guidelines



Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Preheat/Soak		
Temperature Min (T_{smin})	100 °C	150 °C
Temperature Max (T_{smax})	150 °C	200 °C
Time (t_s) from (T_{smin} to T_{smax})	60-120 seconds	60-120 seconds
Ramp-up rate (T_L to T_p)	3 °C/second max.	3 °C/second max.
Liquidous temperature (T_L)	183 °C	217 °C
Time (t_L) maintained above T_L	60-150 seconds	60-150 seconds
Peak package body temperature (T_p)	225 °C	250 °C
Classification temperature (T_c)	230 °C	255 °C
Time (t_p)* within 5 °C of the specified classification temperature (T_c)	20* seconds	30* seconds
Ramp-down rate (T_p to T_L)	6 °C/second max.	6 °C/second max.
Time 25 °C to peak temperature	6 minutes max.	8 minutes max.

Note 1: All temperatures refer to the center of the package, measured on the package body surface that is facing up during assembly reflow (e.g., live-bug).

Figure 4 - Reflow

Package Mechanical Specifications

DFN-8

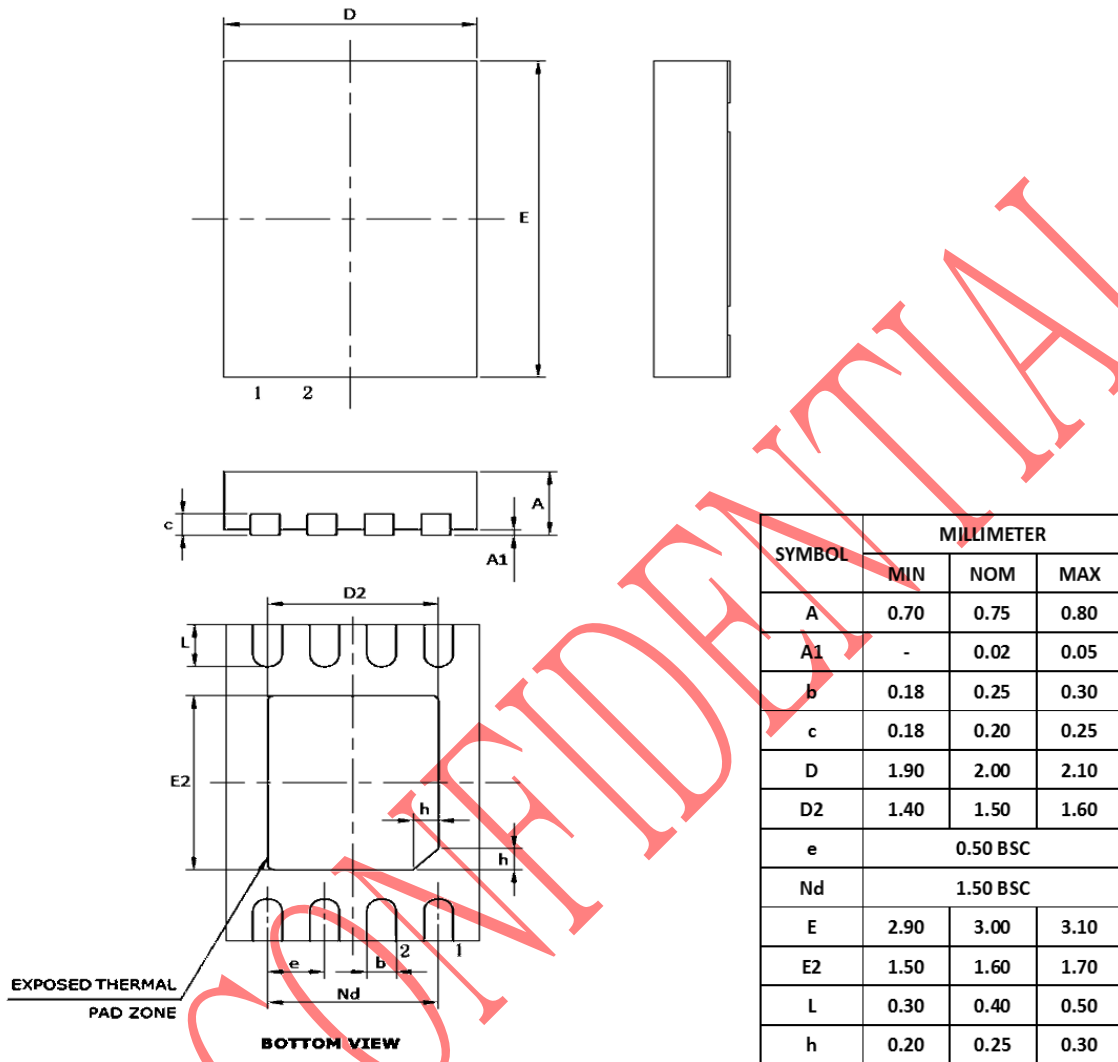


Figure 5 - Mechanical Specification (DFN-8)

WLCSP-6

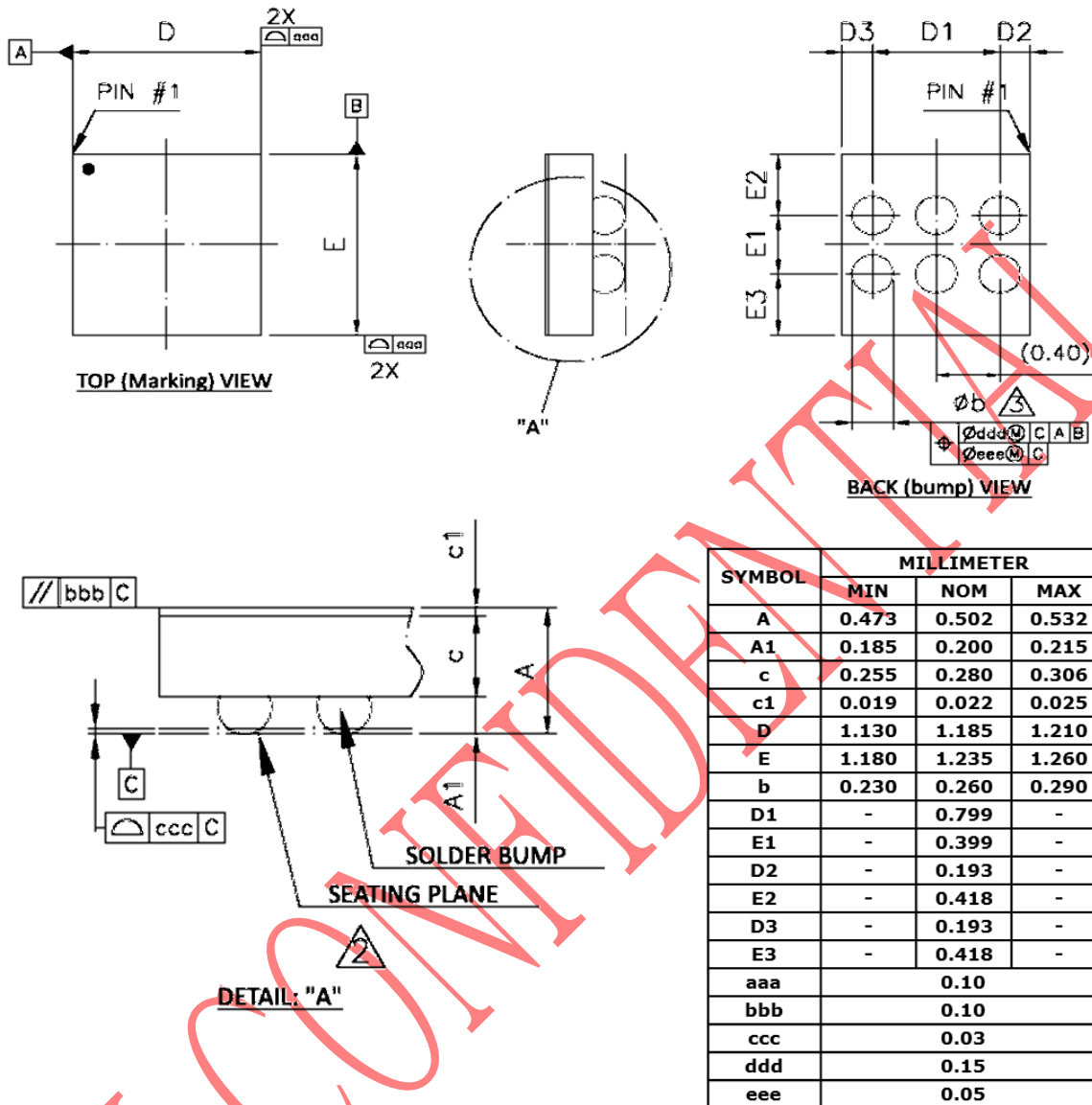


Figure 6 - Mechanical Specification (WLCSP-6)

Package Top Side Marking

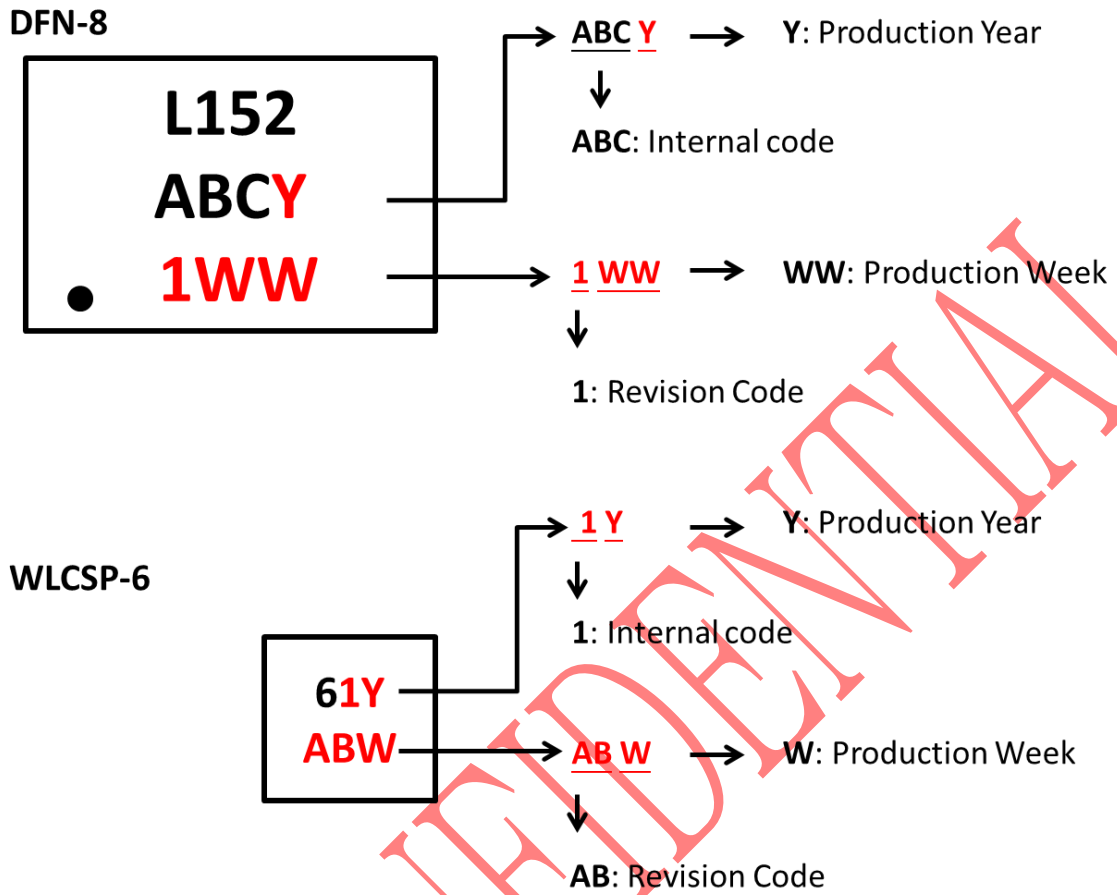


Figure 7 - Package Top Side Marking

Ordering Information

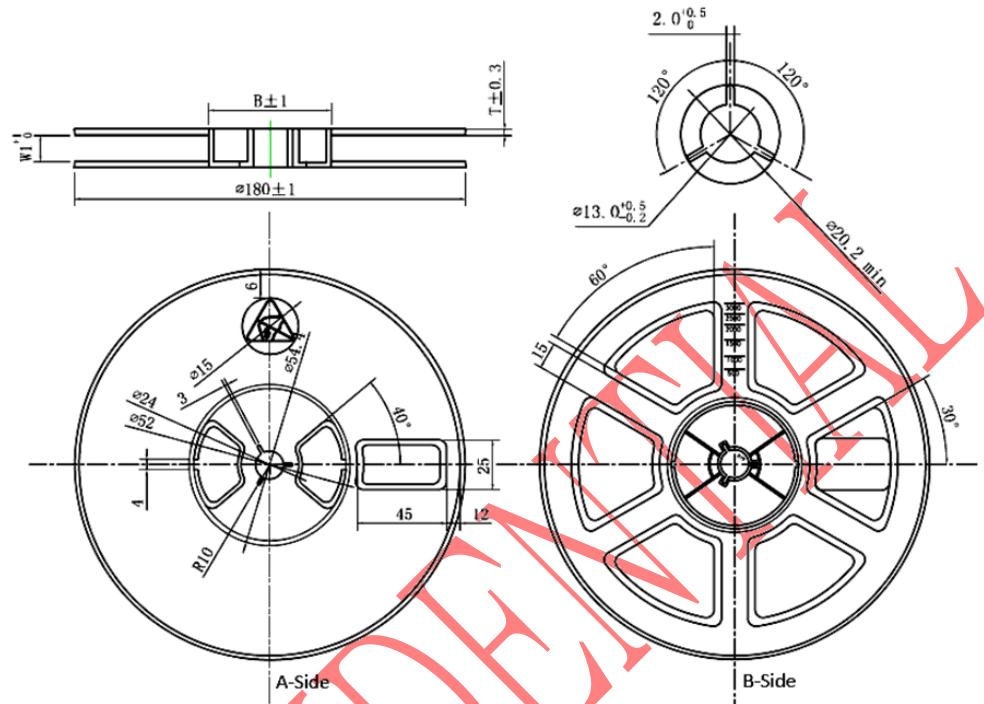
Part Number	Description	Package Type
VL152 (B1)-2	Tape and Reel (3K)	DFN-8 (2x3mm)
VL152 (B1)-W	Tape and Reel (3K)	WLCSP-6 (1.2x1.25mm)

Note: RoHS compliance and HF compliance

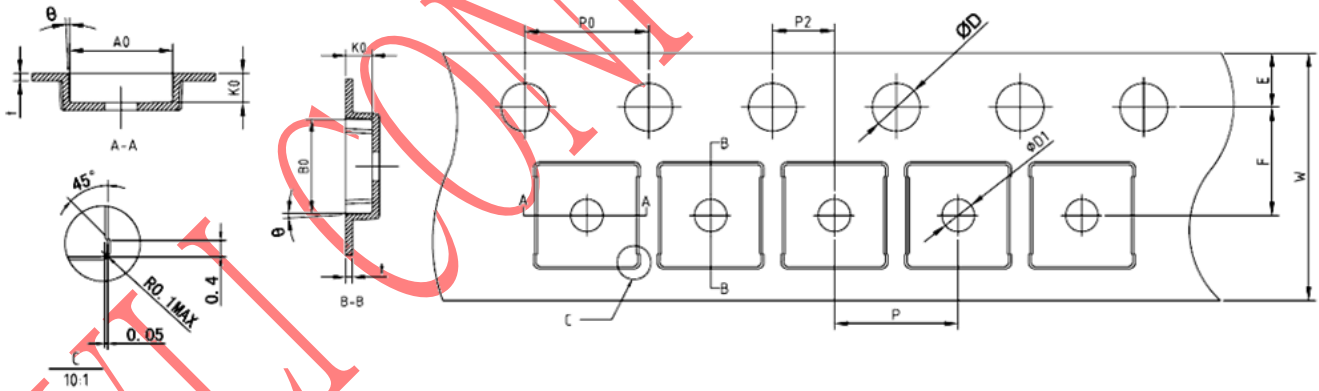
Tape and Reel Information

Reel Dimensions

SYMBOL	(mm)
B	54.4
W1	8.6
T	1.5



Type Dimensions



SYMBOL	(mm)
E	1.75±0.10
F	3.50±0.05
P2	2.00±0.05
D	1.55±0.05
D1	1.05 ^{+0.25} ₀
P0	4.00±0.10
10P0	40.00±0.20

SYMBOL	(mm)
W	8.00 ^{+0.30} _{-0.10}
P	4.00±0.10
A0	3.25±0.10
B0	3.25±0.10
K0	0.95±0.10
t	0.25±0.02
θ	3° TYP

Figure 8 - Tape & Reel Information

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VIA Labs, Inc.

www.via-labs.com

7F, 529-1, Zhongzheng Rd.,
Xindian District, New Taipei City 23148 Taiwan

Tel: (886-2) 2218-1838

Fax: (886-2) 2218-2553

Email: sales@via-labs.com.tw

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